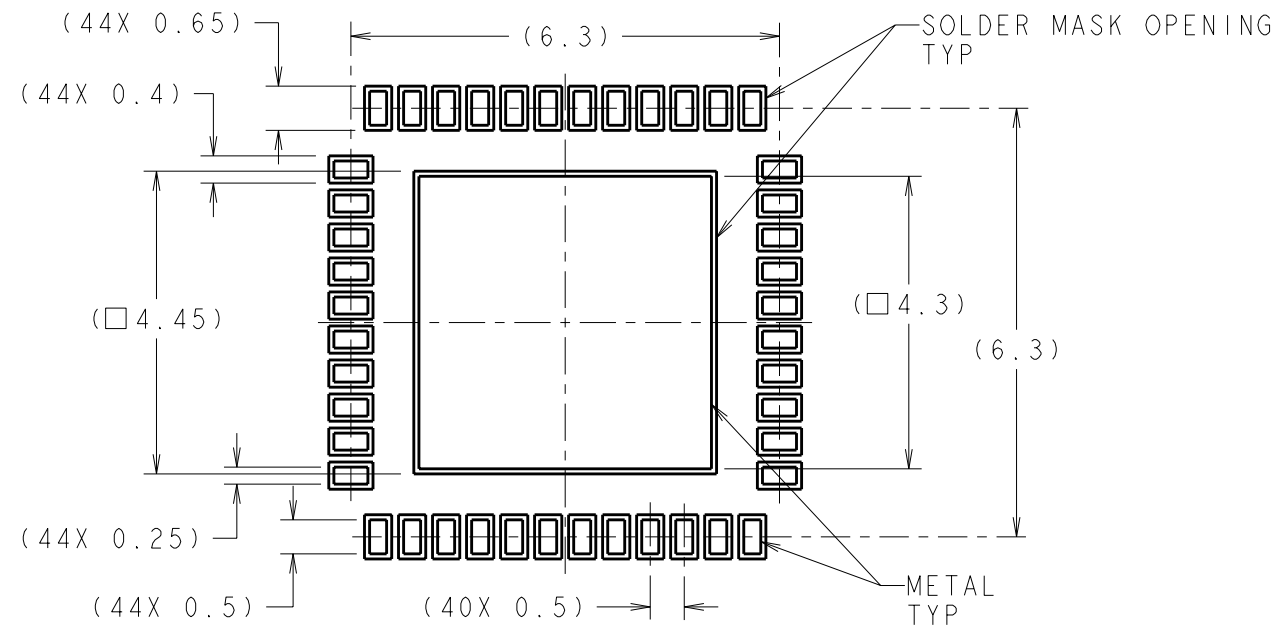
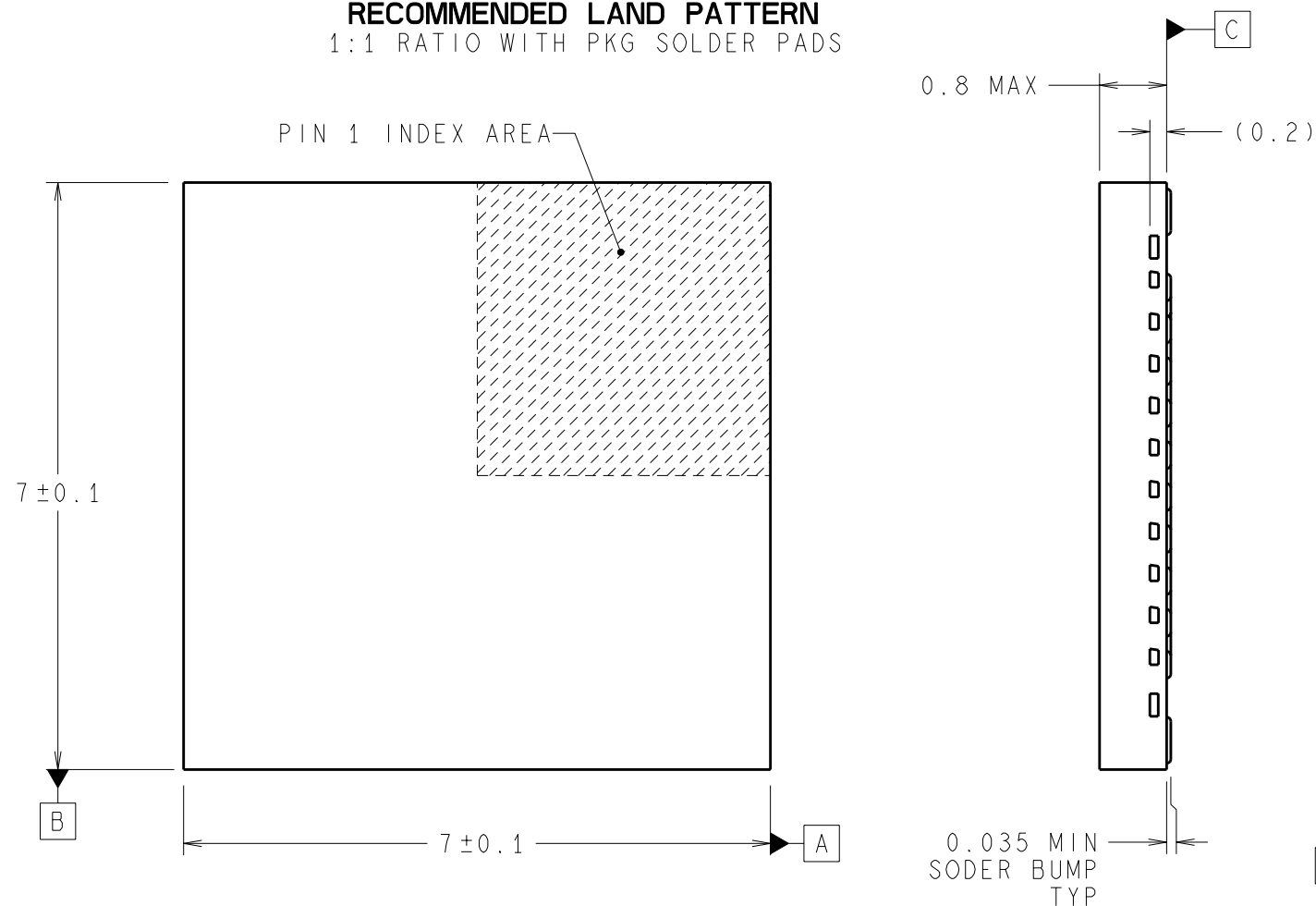


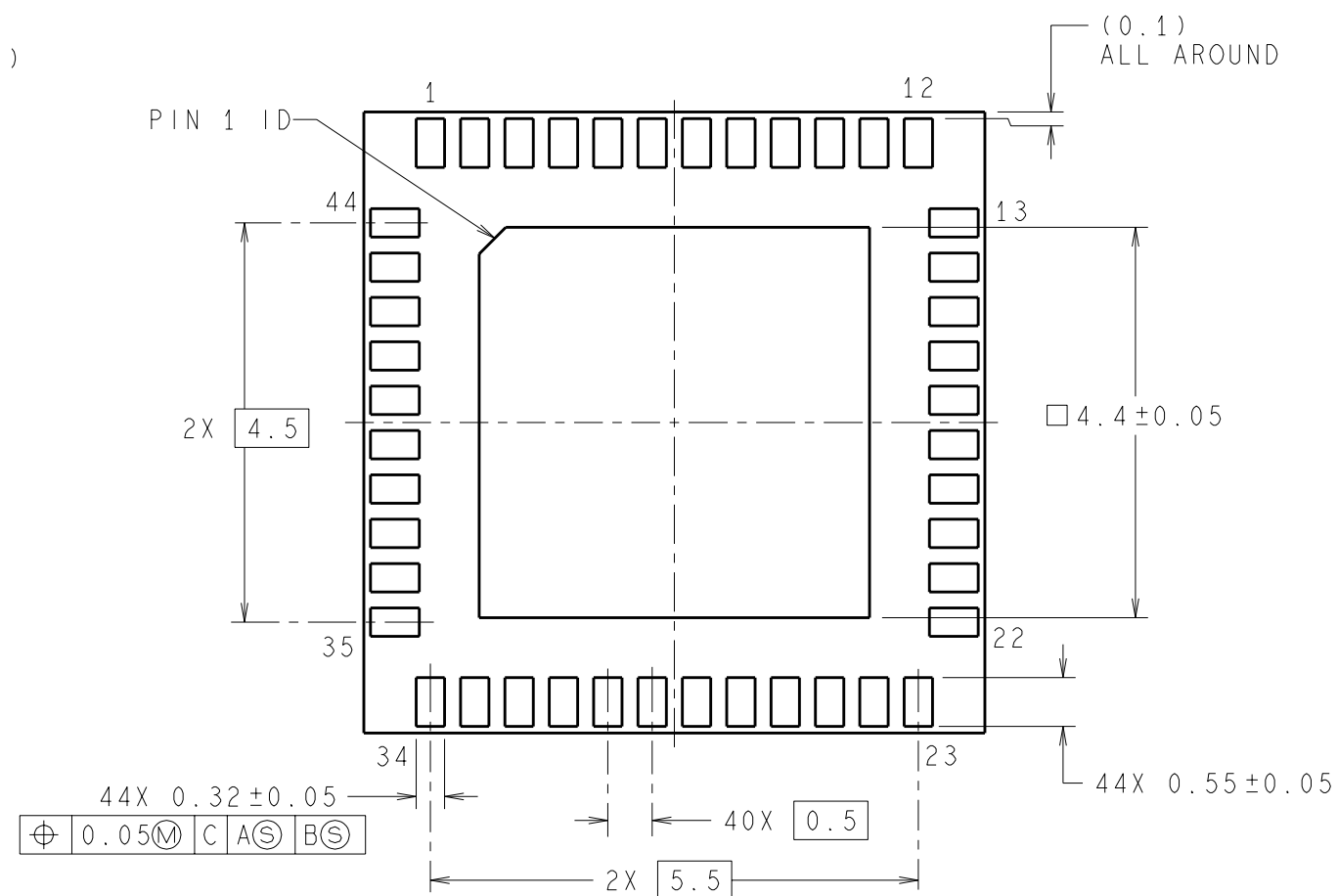
REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	748	06/27/2002	TL/JS
B	DAP S/M OPENING WAS 4.5; DAP TOL. WAS +/-0.1	777	09/10/2002	TL/JS



RECOMMENDED LAND PATTERN
1:1 RATIO WITH PKG SOLDER PADS

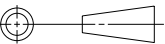


DIMENSIONS ARE IN MILLIMETERS



NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH TO BE 35 MICRONS MINIMUM OF TIN/LEAD SOLDER ON COPPER.
- NO JEDEC REGISTRATION AS OF SEPTEMBER 2002.

APPROVALS		DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRAWN	T. LEQUANG	06/27/2002		
DFTG. CHK.	MARTA SUCHY	09/10/2002	LLP, PLASTIC, QUAD, 7x7x0.75 mm BODY, 44 LD, 0.5 mm PITCH, SOLDER BUMP	
ENGR. CHK.	JEFF SCHAEFER	09/10/2002		
PROJECTION		SCALE	SIZE	DRAWING NUMBER
 MM		NTS	B	(SC)MKT-LQA44C
FORMERLY: X-01904		SHEET 1 of 1		